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PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
TAKASHI NAITO	07/21/2015
SHINICHI TACHIZONO	07/21/2015
KEI YOSHIMURA	07/21/2015
YUJI HASHIBA	07/21/2015
TAIGO ONODERA	07/21/2015
TAKUYA AOYAGI	07/21/2015
TATSUYA MIYAKE	07/21/2015

RECEIVING PARTY DATA

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14838786

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PATENT REEL: 036449 FRAME: 0386

08/28/2015

Total Attachments: 1

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ASSIGNMENT (譲 涟 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizon of Japan by Hitachi Chemical Company, Ltd., a corporation organized under the laws of Japan, located at 9-2, Marunouchi 1-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi Chemical Company, Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, In and to

LEAD-FREE LOW-MELTING GLASS COMPOSITION, LOW-TEMPERATURE SEALING GLASS FRIT, LOW-TEMPERATURE SEALING GLASS PASTE, CONDUCTIVE MATERIAL, AND CONDUCTIVE GLASS PASTE CONTAINING GLASS COMPOSITION, AND GLASS-SEALED COMPONENT AND ELECTRIC/ELECTRONIC COMPONENT PREPARED USING THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi Chemical Company, Ltd., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Palents to issue said Letters Patent to said Hilachi Chemical Company, Ltd.,

Signed on the date(s) indicated aside signatures:

(発明者フルネームサイン) 1) Takashi NAITO Shinichi TACHIZONO

INVENTOR(S)

Kei YOSHIMURA

Yuji HASHIBA

5) Taigo ONODERA

6) Takuya AOYAGI 7) Tatsuya MIYAKE

10) _____

Date Signed (署名目)

1 2015

7/21 '2015

2015

PATENT PATENT REEL: 036449 FRAME: 0388

RECORDED: 08/28/2015